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16 (new). An electronic device package comprising:
an integrated circuit chip having chip pads on a top surface;
a flexible layer overlying the integrated circuit chip, the flexible layer having via openings
ng to the chip pads; and

a pattern of electrical conductors extending over portions of the flexible layer and into the via openings and forming a reconfigured universal array of test and interconnection pads on the flexible layer,

the integrated circuit chip, the flexible layer, and the pattern of electrical conductors forming a known good electronic device package.

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17 (r)

~~17~~ (new). The device in claim ~~16~~ wherein the flexible layer includes at least one resistor and wherein the pattern of electrical conductors couples the at least one resistor to at least one of the test and interconnection pads.

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~~18~~ (new). The device of claim ~~16~~ wherein the flexible layer comprises a polymer.

REMARKS

Approval of the amendments is respectfully requested.

Respectfully submitted,

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